

TIM-LGF-2006

Thermally Conductive, Two Part Silicone Liquid Gap Filler

DESCRIPTIONS

TIM-LGF-2006 is thermally conductive liquid gap filler material formulated with controlled curing functionality to provide a balance of cured material properties and tacky grease like consistency. This Form-In-Place liquid gap filler is ideal for applying any thickness. Unlike cured thermal pad, a liquid approach offers infinite thickness variations with little or no stress to sensitive components during assembly process.

TIM-LGF-2006 flows under pressure like grease, easily cures at room or elevated temperature and form in tacky/gel and adheres to most surfaces, forms shapes and sizes of components with very low compression force. It stays in heavy gel/paste type for life, eliminates oil separation and pump out during thermal cycles. It can be applied like grease, easily dispensable from wide range of commercially available equipment.

KEY FUTURES AND BENEFITS

- **Thermal Conductivity (0.8 W/m-K)**
- Ultra-conforming, wet-out. Designed for fragile and low stress applications
- **Controlled cure, Gelled grease type.**
- Relieves CTE Stress during thermal cycling

APPLICATIONS

- Interface for semiconductors requiring low pressure or spring clamp mounting
- Large cavity/components immersion
- PPGA's, BGA, Micro BGA, DSP chips, LED
- Automotive electronics (ECU's)
- Thermally conductive vibration dampening

AVAILABILITY

50cc & 400cc dual Syringes/Cartridges, 2 gallon & 10 gallons Kits

Property	Test Method	Value
Type		Two Parts Silicone, Partially curable
Special Futures		Very soft/gel type controlled cure. Thermal grease performance, zero bleed, pump-out
Color	Visual	Blue (Part A: White, Part B: Blue)
Mixed Viscosity. PaS	Brookfield	120
Mix Ratio		1:1
Specific Gravity	ASTM D792	2.1
Hardness (Shore 00)	ASTM D2240	Paste/Grease form
Pot Life @ 25°C		24 hrs
Cure Time @ 25°C		24-48 hrs
Cure Time @ 100°C		5 min
Flammability (Equivalent)	UL 94	V-0
Operating Temperature Range.		-55°C to 204°C
Shelf Life (Unopened)		12 months
THERMAL		
Thermal Conductivity (W/m-K)	ASTM D5470	0.8
ELECTRICAL		
Breakdown Voltage (KV/mm)	ASTM D149	12
Volume Resistivity (Ohm-m)	ASTM D257	10 ¹²

DISCLAIMER: All statements, technical information, and recommendations related to Timtronics products are based on information believed to be reliable, but accuracy or completeness is not guaranteed. Before using this product, you must evaluate it and determine if it is suitable for your intended application. You must assume all risks and liability associated with such use. Timtronics will not be liable for any indirect, special, incidental or consequential loss or damage arising from this product, regardless of legal theory asserted.